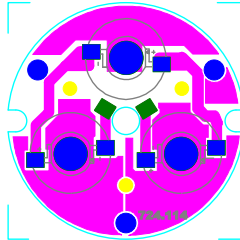


1w Power



Diameter Size: **44 mm**

Thickness: **1,6 mm**

Weight: **5 g**

Electricity Line: **Copper**

Thickness of copper: **35um**

Thickness of the dielectric: **70um**

Thickness of the aluminum-base: **1.5mm**

Lenses for PCB 724-114:



3 B 25 D



3 B 45 D



3 B 50 D



3 B 60 D



3 B 3570 D

The result of the test:

Item	Test item		Technology request	Unit	Test result
1	Peel Strength	A	≥ 1.8	N/mm	2.0
		After thermal stress (260°C)	≥ 1.8	N/mm	1.8
2	Blister test After Thermal stress (288°C , 2min)		288°C, 2 min No delaminating	/	Ok
3	Thermal resistance		≤ 2.0	°C/W	1.0
4	Thermal-Conductive Factor			W/m·k	1.0
5	Flammability(A)		FV-O	/	FV-O
6	Surface Resistivity	A	$\geq 1 \times 10^5$	MΩ	5×10^7
		Constant humidity treatment (90%,35°C,96h)	$\geq 1 \times 10^5$	MΩ	2×10^6
7	Volume Resistivity	A	$\geq 1 \times 10^6$	MΩ·m	4×10^8
		Constant humidity treatment (90%,35°C,96h)	$\geq 1 \times 10^6$	MΩ·m	5×10^7
8	Dielectric Breakdown(DC)		≥ 28.5	KV/MM	31
9	Dielectric constant(1MHz) (40°C, 93%, 96h)		≤ 4.4	/	4.2
10	Dielectric dissipation factor (1MHz) (40°C , 93% , 96h)		≤ 0.03	/	0.02

